ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				aterials and	als and Mfg Information				
upplier	Information														
Company name* Company unique ID				Unique ID Authority				Respo	Response Date*						
nsemi											2024-	2024-04-30			
Contact Na	nme		Title - Contact]	Phone - Contact*				Emai	Email - Contact*			
Product-E	nv-Stewards		Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative]	Phone - Representative*				Emai	Email - Representative*				
Product-Env-Stewards Product 1				ro Compliance	npliance NA Product-Env-Stewards@onsen					ards@onsemi.co	om				
	Requester Item Number Mfr Item		Number	Mfr Item Name			Effective Date	Version	Ν	Ianufacturing Si	e	Weight*	ght* UOM Unit Type		
	NFAM3065L4BT 3 Phase Inverter IF		PM		2024-04-30		1	VN5		8944.253	mg	Each			
Ianufac	turing Proccess Informat	tion													
7	Terminal Plating / Grid Array Material		erminal Base	Alloy J-STD-020 MSI		L Rating	Peak Proc	Peak Process Body Temperat		ture Max Time at Peak Ter		rature Numb	er of Reflow Cy	cles	
I	Matte Tin (Sn) - annealed CU A		CU Alloy	I	NA		0		С	30	sec	conds 3			
omments															
or more ir	nformation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.												
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	461.068	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		184.4272	mg
			Supplier	Copper (Cu)	7440-50-8		276.6408	mg
Die	51.5022	mg	Supplier	Silicon (Si)	7440-21-3		51.5022	mg
Die Attach	1.41124	mg		Epoxy resin	proprietary data		0.2173	mg
			Supplier	Imidazole Addition	68490-66-4		0.0226	mg
			Supplier	Silver (Ag)	7440-22-4		1.0867	mg
			В	Bismuth Trioxide (Bi2O3)	1304-76-3		0.0607	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.024	mg
Die Attach Solder	4.19991	mg	Supplier	Silver (Ag)	7440-22-4		0.105	mg
			Supplier	Tin (Sn)	7440-31-5		4.0739	mg
			Supplier	Copper (Cu)	7440-50-8		0.021	mg
Lead Frame	462.339	mg	Supplier	Silver (Ag)	7440-22-4		23.1169	mg
			Supplier	Zinc (Zn)	7440-66-6		0.5548	mg
			Supplier	Iron (Fe)	7439-89-6		11.0961	mg
			Supplier	Copper (Cu)	7440-50-8		427.2012	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3699	mg
Mold Compound-Black	7922.92	mg	Supplier	Carbon Black (C)	1333-86-4		79.2292	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6734.4819	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1109.2087	mg
NTC	4.6965	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.2001	mg
			Supplier	Silver (Ag)	7440-22-4		0.047	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0122	mg
			Supplier	Tin (Sn)	7440-31-5		0.078	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		0.9999	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0348	mg
			Supplier	Palladium (Pd)	7440-05-3		0.1099	mg
			Supplier	Iron Trioxide (Fe2O3)	1309-37-1		0.2001	mg
			В	Nickel (Ni)	7440-02-0		0.0333	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		2.6	mg
			Supplier	Copper (Cu)	7440-50-8		0.3814	mg
Plating	0.16692	mg	Supplier	Tin (Sn)	7440-31-5		0.1669	mg
Solder Wire	7.24278	mg	A	Lead (Pb)	7439-92-1	7a	6.8806	mg

			Supplier	Tin (Sn)	7440-31-5	0.3621	mg
Wire Bond - Al	28.5763	mg	Supplier	Aluminum (Al)	7429-90-5	28.5763	mg
Wire Bond - Cu	0.1304	mg	Supplier	Copper (Cu)	7440-50-8	0.1304	mg